

PCN Number:	20190718001.1		PCN Date:	Jul 22, 2019																			
Title:	Qualification of additional Fab site (RFAB) and Assembly site (JCET) options for select devices																						
Customer Contact:	PCN Manager		Dept:	Quality Services																			
Proposed 1st Ship Date:	Oct 22, 2019		Estimated Sample Availability:	Date provided at sample request.																			
Change Type:																							
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																		
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																		
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																		
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																		
		<input type="checkbox"/>	Part number change																				
PCN Details																							
Description of Change:																							
Texas Instruments is pleased to announce the qualification of an additional Fab site (RFAB) and Assembly site (JCET) options for the selected devices listed in the "Product Affected" section.																							
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>MIHO8</td> <td>LBC7</td> <td>200 mm</td> <td>RFAB</td> <td>LBC7</td> <td>300 mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm
Current Fab Site			Additional Fab Site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																		
MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm																		
No Assembly Material Differences between sites. Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Continuity of Supply																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Anticipated impact on Material Declaration																							
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .																				
Changes to product identification resulting from this PCN:																							
Fab Site Information:																							
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																				
MIHO8	MH8	JPN	Ibaraki																				
RFAB	RFB	USA	Richardson																				
Assembly Site Information:																							
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly Site City																				
JCET C3	JCE	CHN	Jiangyin																				
JCET C8	JC8	CHN	Suqian																				
Sample product shipping label (not actual product label)																							



MADE IN: Malaysia
2DC: 20:



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SNE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

MSL 2 / 260C / 1 YEAR SEAL DT
MSL 1 / 235C / UNLIM 03/29/04

OPT:
ITEM: 39
LBL: 5A (L) TO: 1750

Product Affected:

PTPS54202DDCR	SN1704026DDCT	TPS54202HDDCR	TPS54302DDCR
PTPS54202DDCT	TPS54202DDCR	TPS54202HDDCT	TPS54302DDCT
SN1704026DDCR	TPS54202DDCT		

Qualification Report

SN1704026DDC

Approve Date 26-Jun-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN1704026DDC	QBS Product Reference: TPS54202HDDC	QBS Product Reference: TPS54302DDC	QBS Product Reference: TPS563208DDC	QBS Process Reference: TPS65265RHB
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass
HBM	ESD - HBM	4000V	1/3/0	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	-	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	-	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	-	3/231/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb-Free Solder	-	-	-	3/66/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb Solder	-	-	-	3/66/0	-

- QBS: Qual By Similarity
 - Qual Device SN1704026DDC is qualified at LEVEL1-260C
 - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

Qualification Report

TPS54202DDC TPS54202HDDC TPS54302DDC
Approve Date 26-Jun-2019

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS54202DDC	Qual Device: TPS54202HDDC	Qual Device: TPS54302DDC	QBS Product Reference: TPS563208DDC	QBS Process Reference: TPS65265RHB
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass
HBM	ESD - HBM	4000V	1/3/0	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	-	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	-	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	-	3/231/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb-Free Solder	-	-	-	3/66/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb Solder	-	-	-	3/66/0	-

- QBS: Qual By Similarity
- Qual Device TPS54202HDDC is qualified at LEVEL1-260C
- Qual Device TPS54302DDC is qualified at LEVEL1-260C
- Qual Device TPS54202DDC is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

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